



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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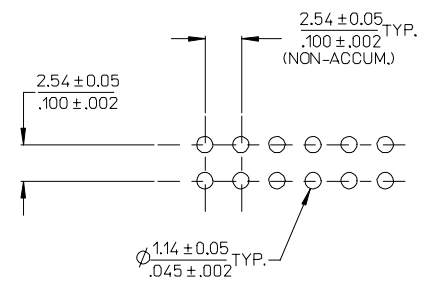
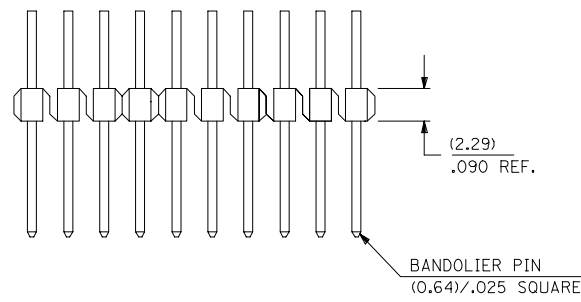
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



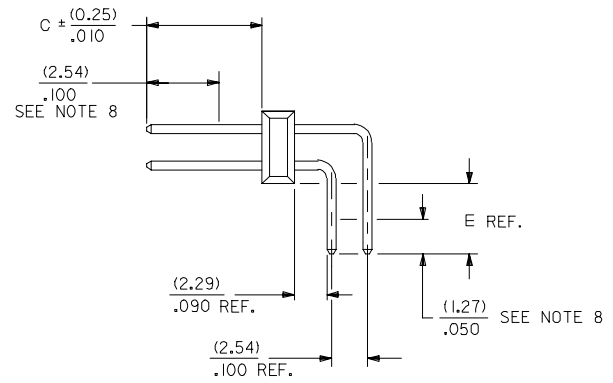
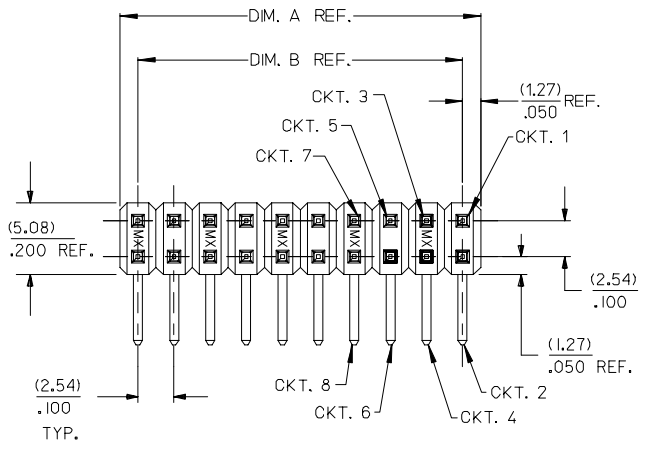
13 12 11 10 9 8 7 6 5 4 3 2 1

J
I
H
G
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E
D
C
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A

CKTS	DIM. A	DIM. B
04	(5.08)/.200	(2.54)/.100
06	(7.62)/.300	(5.08)/.200
08	(10.16)/.400	(7.62)/.300
10	(12.70)/.500	(10.16)/.400
12	(15.24)/.600	(12.70)/.500
14	(17.78)/.700	(15.24)/.600
16	(20.32)/.800	(17.78)/.700
18	(22.86)/.900	(20.32)/.800
20	(25.40)/1.000	(22.86)/.900
22	(27.94)/1.100	(25.40)/1.000
24	(30.48)/1.200	(27.94)/1.100
26	(33.02)/1.300	(30.48)/1.200
28	(35.56)/1.400	(33.02)/1.300
30	(38.10)/1.500	(35.56)/1.400



RECOMMENDED P.C. BOARD HOLE LAYOUT



- NOTES:
- MATERIAL: WAFER - HIGH TEMPERATURE THERMAL PLASTIC, 94V-0; COLOR: BLACK
PIN - COPPER ALLOY
 - PLATING:
 - TIN - (0.00381)/.000150 MINIMUM TIN PLATE OVER NICKEL PLATE.
 - 15 GOLD - (0.00038)/.000015 MINIMUM GOLD PLATE IN SELECT AREA. (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
 - 30 GOLD - (0.00076)/.000030 MINIMUM GOLD PLATE IN SELECT AREA. (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
 - * THE PRIMARY SHIPPING CARTON WILL BE LABELED 'COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'. CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
 - PRODUCT CONFORMS TO PS-71764.
 - PACKAGING INFORMATION:
 - FOR 4 THRU 8 CIRCUIT PARTS USE PK-70873-0353
 - FOR 10 CIRCUITS AND OVER USE PK-70873-0075
 - FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
 - PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN AT BANDOLIER PIN FAYING SURFACE. (APPROX. (0.64)/.025 LNG X (0.15)/.006 WD. REF.) 2 LOCATIONS
 - WAFER TO BE FLAT WITHIN (0.03 MM/CM) OR .003 IN./IN
 - MEASURE POINT FOR PLATING THICKNESS.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002

2	A
1	A1
SHT.	REV.

ADD NOTE 9 EC NO: UCP2007-1441 DRAWN/PRD: 2006/12/11 CHKD: ADERR 2006/12/11 APPR: FSM TH 2006/12/12	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± .01 2 PLACES ± 0.25 ± .01 1 PLACE ± 0.25 ± --- ANGULAR ±1/2°	mm INCH DRAWN BY DATE CAC 1995/08/23 CHECKED BY DATE PR 1995/08/23 APPROVED BY DATE DJB 1995/08/23	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-71764-001		SHEET NO. 1 OF *	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

12 11 10 9 8 7 6 5 4 3 2 1

ITEM NO: 71764-0004/0030, 9003			ITEM NO: 71764-0104/0130, 9001, 9004			ITEM NO: 71764-0204/0230, 9000, 9002		
DIM. C		(6.10)/.240	DIM. C		(6.10)/.240	DIM. C		(6.10)/.240
DIM. E (REF.)		(2.79)/.110	DIM. E (REF.)		(2.79)/.110	DIM. E (REF.)		(2.79)/.110
FINISH		TIN	FINISH		15 GOLD	PLATING FINISH		30 GOLD
CONNECTOR END PLATING		TIN	CONNECTOR END PLATING		GOLD	CONNECTOR END PLATING		GOLD
P.C. BOARD END PLATING		TIN	P.C. BOARD END PLATING		TIN	P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1	PACKAGING		SEE NOTE 4 SHEET 1	PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS	CKTS	ITEM NUMBER	VOIDS	CKTS	ITEM NUMBER	VOIDS
04	71764-0004		04	71764-0104		04	71764-0204	
06	71764-0006		06	71764-0106		06	71764-0206	
08	71764-0008		08	71764-0108		08	71764-0208	
10	71764-0010		10	71764-0110		10	71764-0210	
12	71764-0012		12	71764-0112		12	71764-0212	
14	71764-0014		14	71764-0114		14	71764-0214	
16	71764-0016		16	71764-0116		16	71764-0216	
18	71764-0018		18	71764-0118		18	71764-0218	
20	71764-0020		20	71764-0120		20	71764-0220	
22	71764-0022		22	71764-0122		22	71764-0222	
24	71764-0024		24	71764-0124		24	71764-0224	
26	71764-0026		26	71764-0126		26	71764-0226	
28	71764-0028		28	71764-0128		28	71764-0228	
30	71764-0030		30	71764-0130		30	71764-0230	
06	71764-9003	3	06	71764-9001	3, 4	06	71764-9002	3, 4
			08	71764-9004	5, 6			
						10	71764-9000	8

A	REV:	ECR/ECN INFORMATION	TITLE:	DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS	SHEET No.
		EC No: UCP2007-0449			- 2 -
		DATE: 2006-08-18			
DOCUMENT NUMBER:		CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:	
SD-71764-001		PRIDDER	ADERR	FSMITH	

